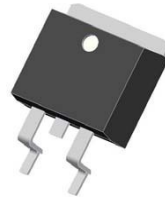
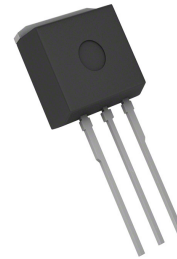


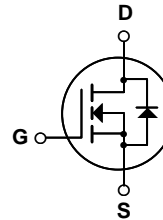
**TO-263**

**TO-262**

**Features**

- 32A, 60V,  $R_{DS(on)} = 0.035\Omega$  @  $V_{GS} = 10\text{ V}$
- Low gate charge ( typical 15 nC)
- Low Crss ( typical 50 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability
- 175°C maximum junction temperature rating

**General Description**

These N-Channel enhancement mode power field effect transistors are produced using Kersemi proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for low voltage applications such as automotive, DC/DC converters, and high efficiency switching for power management in portable and battery operated products.


**Absolute Maximum Ratings**  $T_C = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	KSMB30N06L / KSMI30N06L	Units
$V_{DSS}$	Drain-Source Voltage	60	V
$I_D$	Drain Current - Continuous ( $T_C = 25^\circ\text{C}$ )	32	A
	- Continuous ( $T_C = 100^\circ\text{C}$ )	22.6	A
$I_{DM}$	Drain Current - Pulsed (Note 1)	128	A
$V_{GSS}$	Gate-Source Voltage	$\pm 20$	V
$E_{AS}$	Single Pulsed Avalanche Energy (Note 2)	350	mJ
$I_{AR}$	Avalanche Current (Note 1)	32	A
$E_{AR}$	Repetitive Avalanche Energy (Note 1)	7.9	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	7.0	V/ns
$P_D$	Power Dissipation ( $T_A = 25^\circ\text{C}$ ) *	3.75	W
	Power Dissipation ( $T_C = 25^\circ\text{C}$ )	79	W
	- Derate above 25°C	0.53	W/°C
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +175	°C
$T_L$	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	°C

**Thermal Characteristics**

Symbol	Parameter	Typ	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	--	1.90	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *	--	40	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	--	62.5	°C/W

\* When mounted on the minimum pad size recommended (PCB Mount)

**Electrical Characteristics**
 $T_C = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
<b>Off Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$	60	--	--	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250\ \mu\text{A}$ , Referenced to $25^\circ\text{C}$	--	0.06	--	V/ $^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 60\text{ V}, V_{GS} = 0\text{ V}$	--	--	1	$\mu\text{A}$
		$V_{DS} = 48\text{ V}, T_C = 150^\circ\text{C}$	--	--	10	$\mu\text{A}$
$I_{GSSF}$	Gate-Body Leakage Current, Forward	$V_{GS} = 20\text{ V}, V_{DS} = 0\text{ V}$	--	--	100	nA
$I_{GSSR}$	Gate-Body Leakage Current, Reverse	$V_{GS} = -20\text{ V}, V_{DS} = 0\text{ V}$	--	--	-100	nA

**On Characteristics**

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\ \mu\text{A}$	1.0	--	2.5	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 10\text{ V}, I_D = 16\text{ A}$	--	0.027	0.035	$\Omega$
		$V_{GS} = 5\text{ V}, I_D = 16\text{ A}$	--	0.035	0.045	$\Omega$
$g_{FS}$	Forward Transconductance	$V_{DS} = 25\text{ V}, I_D = 16\text{ A}$ (Note 4)	--	24	--	S

**Dynamic Characteristics**

$C_{iss}$	Input Capacitance	$V_{DS} = 25\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$	--	800	1040	pF
$C_{oss}$	Output Capacitance		--	270	350	pF
$C_{rss}$	Reverse Transfer Capacitance		--	50	65	pF

**Switching Characteristics**

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 30\text{ V}, I_D = 16\text{ A},$ $R_G = 25\ \Omega$	--	15	40	ns
$t_r$	Turn-On Rise Time		--	210	430	ns
$t_{d(off)}$	Turn-Off Delay Time		--	60	130	ns
$t_f$	Turn-Off Fall Time		(Note 4, 5)	--	110	230
$Q_g$	Total Gate Charge	$V_{DS} = 48\text{ V}, I_D = 32\text{ A},$ $V_{GS} = 5\text{ V}$	--	15	20	nC
$Q_{gs}$	Gate-Source Charge		--	3.5	--	nC
$Q_{gd}$	Gate-Drain Charge		(Note 4, 5)	--	8.5	--

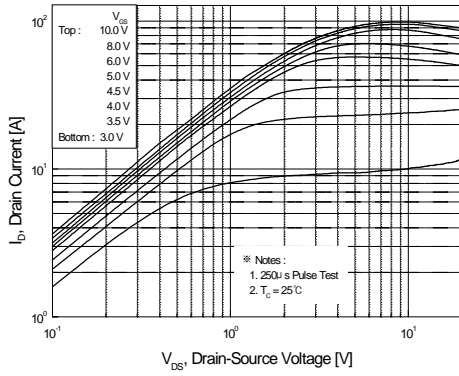
**Drain-Source Diode Characteristics and Maximum Ratings**

$I_S$	Maximum Continuous Drain-Source Diode Forward Current	--	--	32	A	
$I_{SM}$	Maximum Pulsed Drain-Source Diode Forward Current	--	--	128	A	
$V_{SD}$	Drain-Source Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_S = 32\text{ A}$	--	--	1.5	V
$t_{rr}$	Reverse Recovery Time	$V_{GS} = 0\text{ V}, I_S = 32\text{ A},$	--	60	--	ns
$Q_{rr}$	Reverse Recovery Charge	$di_F / dt = 100\text{ A}/\mu\text{s}$ (Note 4)	--	90	--	nC

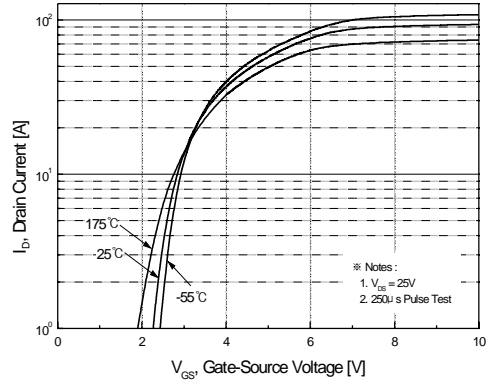
**Notes:**

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2.  $L = 400\ \mu\text{H}, I_{AS} = 32\text{ A}, V_{DD} = 25\text{ V}, R_G = 25\ \Omega$ , Starting  $T_J = 25^\circ\text{C}$
3.  $I_{SD} \leq 32\text{ A}, di/dt \leq 300\text{ A}/\mu\text{s}, V_{DD} \leq BV_{DSS}$ , Starting  $T_J = 25^\circ\text{C}$
4. Pulse Test : Pulse width  $\leq 300\ \mu\text{s}$ , Duty cycle  $\leq 2\%$
5. Essentially independent of operating temperature

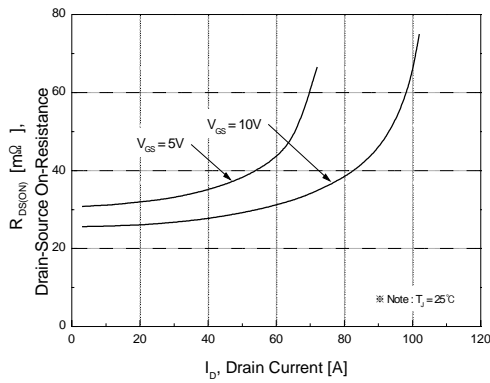
### Typical Characteristics



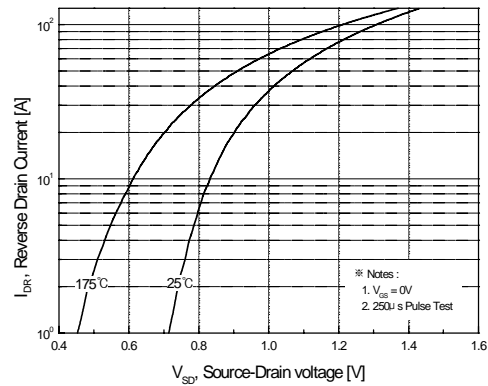
**Figure 1. On-Region Characteristics**



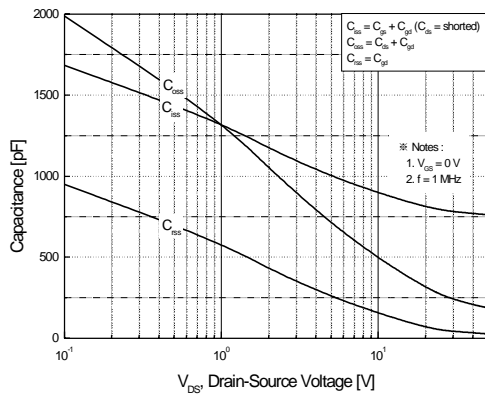
**Figure 2. Transfer Characteristics**



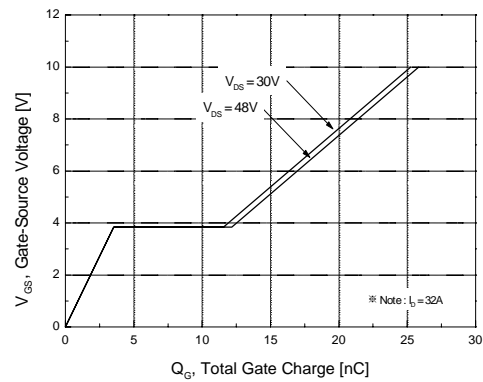
**Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage**



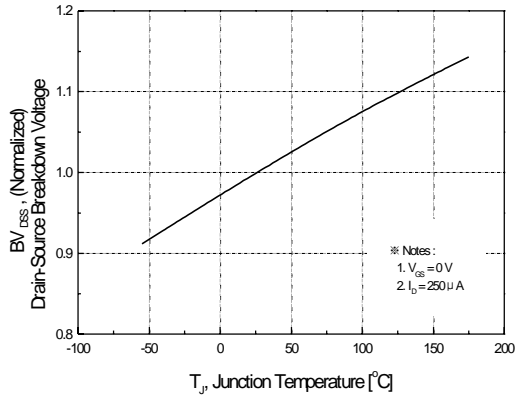
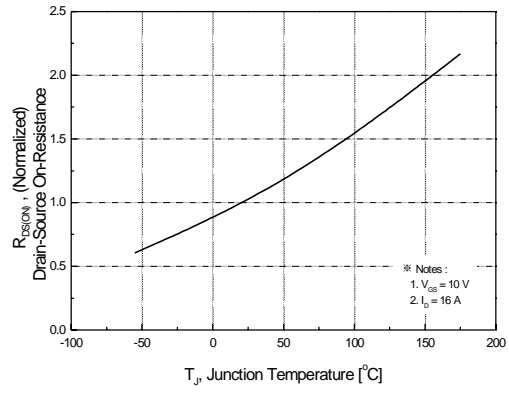
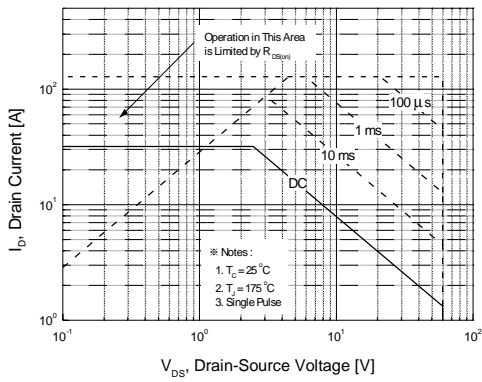
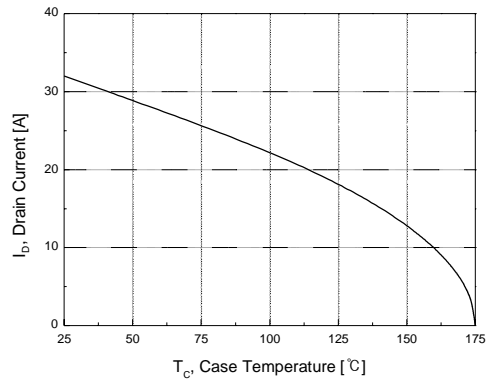
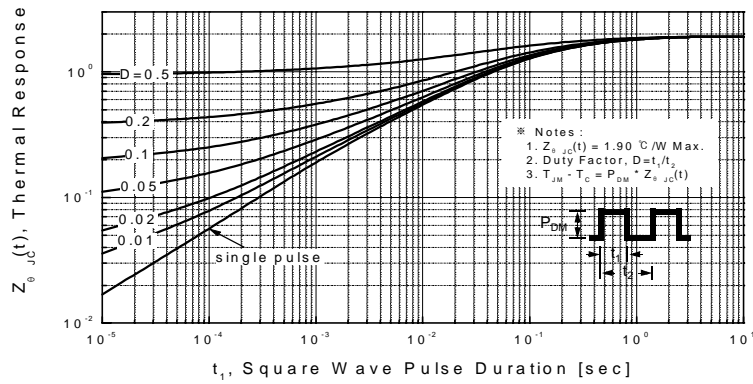
**Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature**

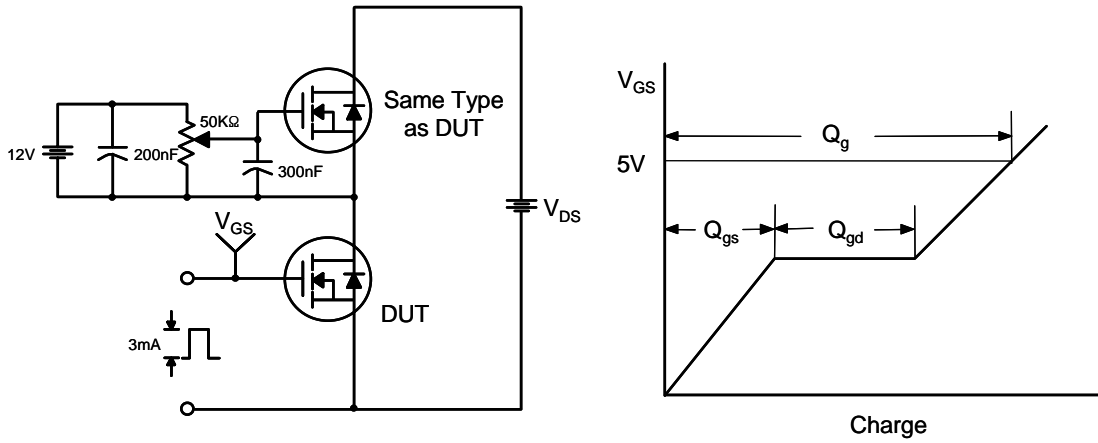
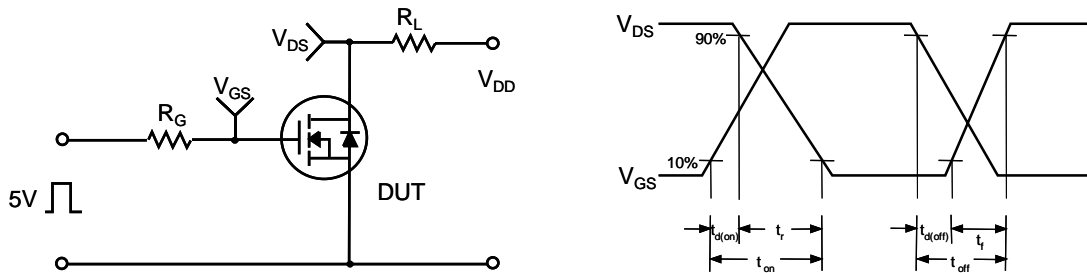
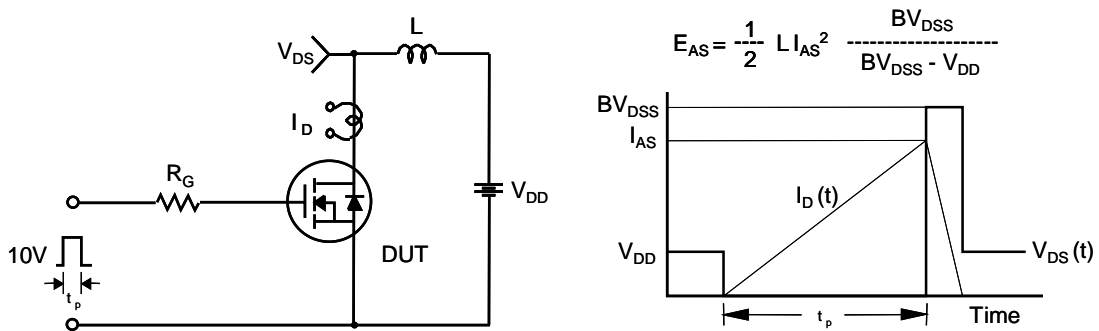


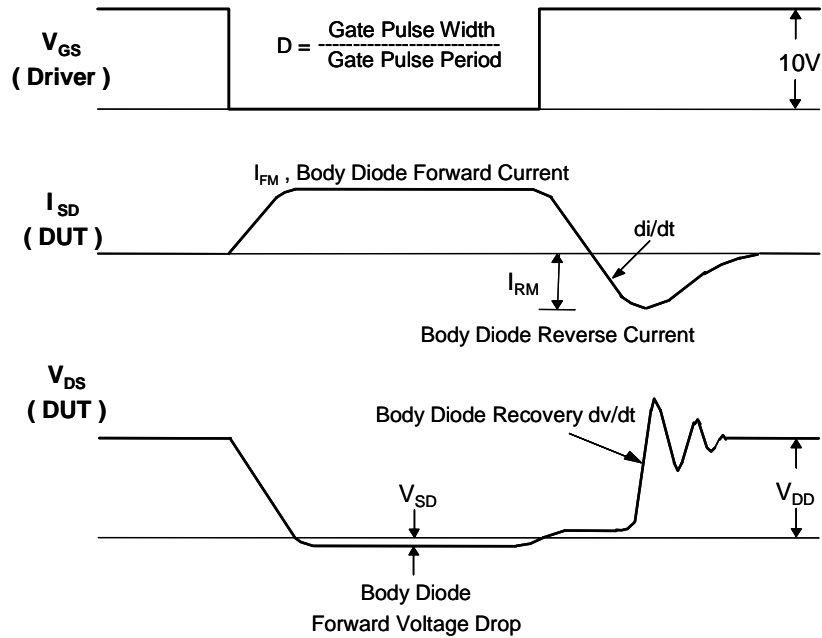
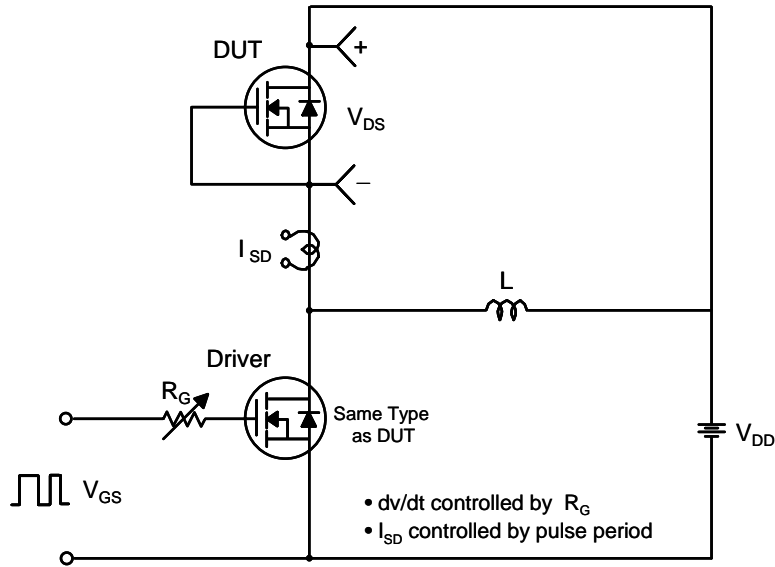
**Figure 5. Capacitance Characteristics**

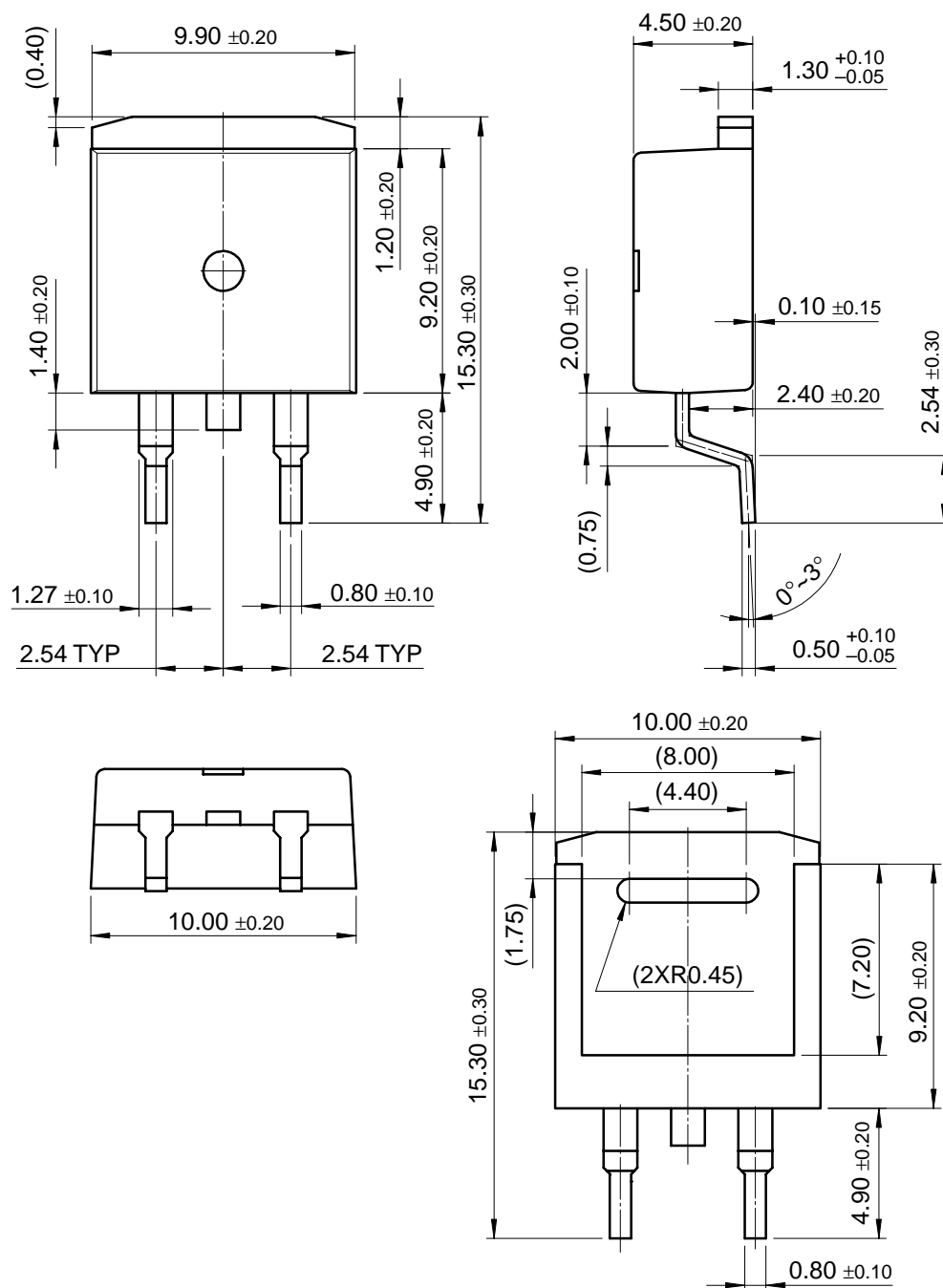


**Figure 6. Gate Charge Characteristics**

**Typical Characteristics (Continued)**

**Figure 7. Breakdown Voltage Variation vs. Temperature**

**Figure 8. On-Resistance Variation vs. Temperature**

**Figure 9. Maximum Safe Operating Area**

**Figure 10. Maximum Drain Current vs Case Temperature**

**Figure 11. Transient Thermal Response Curve**

**Gate Charge Test Circuit & Waveform**

**Resistive Switching Test Circuit & Waveforms**

**Unclamped Inductive Switching Test Circuit & Waveform**


**Peak Diode Recovery dv/dt Test Circuit & Waveforms**


**Package Dimensions**
**D<sup>2</sup>PAK**


**Package Dimensions** (Continued)

**I<sup>2</sup>PAK**

